ASSOCIATION CONNECTING LECTRONICS INDUSTRIES® Material Compositio © Copyright 2005. IPC, Ba international and Pan-Ame	annockburn, Illinois. A	All rights reserved un ntions.	nder both This documents	ment is a declar , the declaratio	ration of the su n encompasse	ubstances s all lower	within the manufacture r level materials for wh	er listed iter hich the mar	m. Note: if th nufacturer ha	e item is an ass s engineering r	embly with lower esponsibility.
				Type * Declaration Class * oute Class 6 - RoHS Yes/No, Homogeneous Mater				ials and Mfg Information			
Supplier Information											
Company name*	Company un	pany unique ID		Unique ID Authority				Response Date*			
nsemi								2023-06-08			
Contact Name	ct Name Title - Contact			Phone - Contact*				Email - Contact*			
Product-Env-Stewards	duct-Env-Stewards Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Authorized Representative*	· ·			Phone - Representative*				Email - Representative*			
Product-Env-Stewards Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Requester Item Number N	Ifr Item Number	Mfr Item Name		Effective Da	te Version	Ν	Manufacturing Site		eight*	UOM	Unit Type
N	CP43080DDR2G Secondary Side S Driver for High E		nchronous Rectification ficiency SMPS Topologie	2023-06-08		PH1		71	.91	mg	Each
Manufacturing Proccess Information											
Terminal Plating / Grid Array Material	rial Terminal Base Alloy		-STD-020 MSL Rating	Peak Process Boo		Temperature Max Time at Peak		Temperatur	e Number	of Reflow Cycl	es
Matte Tin (Sn) - annealed	Matte Tin (Sn) - annealed CU Alloy			260 C		30	seconds	3			
Comments											
ATTENTION: MSL 3 Rated item requires Bake	e and Dry Pack (afte	r electrical test)									
For more information regarding material comp	osition please refer to	o page 3									

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all					
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature Ra	stislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.33	mg	Supplier	Silicon (Si)	7440-21-3		1.33	mg
Die Attach	2.4	mg	Supplier	Organic peroxide	3006-86-8		0.018	mg
			Supplier	Diluent B	Proprietary Data		0.12	mg
			Supplier	Diluent A	Proprietary Data		0.096	mg
			Supplier	Dicyandiamine	461-58-5		0.006	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		1.92	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.24	mg
Lead Frame	37.61	mg	Supplier	Silver (Ag)	7440-22-4		0.1128	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0715	mg
			Supplier	Iron (Fe)	7439-89-6		0.9741	mg
			Supplier	Copper (Cu)	7440-50-8		36.399	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0527	mg
Mold Compound-Black	28.58	mg		Epoxy resin	proprietary data		1.429	mg
			Supplier	Phenolic Resin	Proprietary Data		1.429	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.5716	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1429	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		25.0075	mg
lating	1.89	mg	Supplier	Tin (Sn)	7440-31-5		1.89	mg
Wire Bond	0.1	mg	Supplier	Palladium (Pd)	7440-05-3		0.0021	mg
			Supplier	Gold (Au)	7440-57-5		0.0003	mg
			Supplier	Copper (Cu)	7440-50-8		0.0976	mg